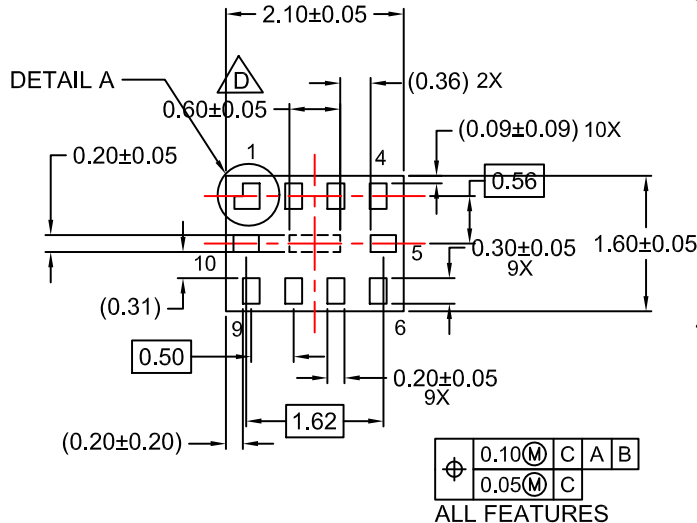
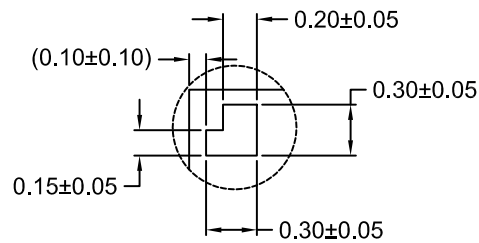
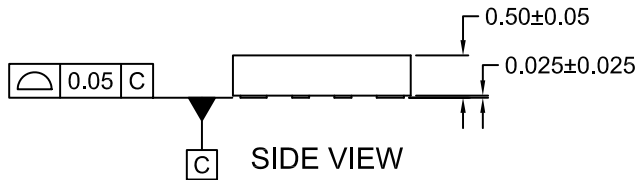
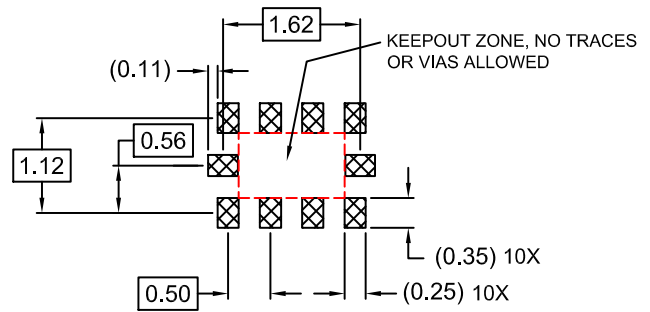
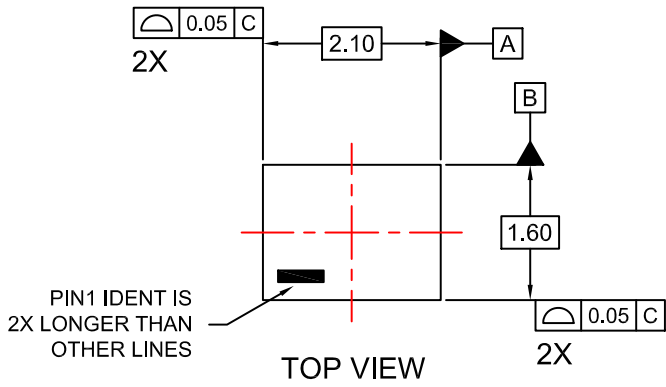


UQFN10 1.6X2.1, 0.5P
CASE 523AZ
ISSUE 0

DATE 31 AUG 2016



- NOTES:**
- A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD .
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
 - D. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.
 - E. DIMENSIONS WITHIN () ARE UNCONTROLLED

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NEW STANDARD:		
DESCRIPTION:	UQFN10 1.6X2.1, 0.5P	PAGE 1 OF 2

